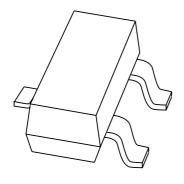
DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS5350T 50 V, 3 A PNP low V_{CEsat} (BISS) transistor

Product specification Supersedes data of 2002 Aug 08 2004 Jan 13





50 V, 3 A PNP low V_{CEsat} (BISS) transistor

PBSS5350T

FEATURES

- Low collector-emitter saturation voltage V_{CEsat} and corresponding low R_{CEsat}
- · High collector current capability
- High collector current gain
- Improved efficiency due to reduced heat generation.

APPLICATIONS

- · Power management applications
- Low and medium power DC/DC convertors
- · Supply line switching
- · Battery chargers
- Linear voltage regulation with low voltage drop-out (LDO).

DESCRIPTION

PNP low V_{CEsat} transistor in a SOT23 plastic package. NPN complement: PBSS4350T.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PBSS5350T	ZD*

Note

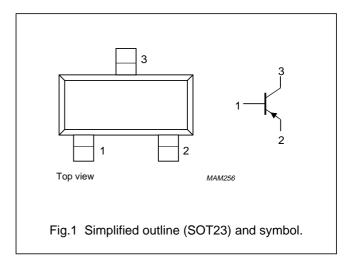
- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-50	V
I _C	collector current (DC)	-2	Α
I _{CRP}	repetitive peak collector current	-3	А
R _{CEsat}	equivalent on-resistance	135	mΩ

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



ORDERING INFORMATION

TYPENUMBER	PACKAGE		
TIPLINOMBLK	NAME DESCRIPTION VERSION		VERSION
PBSS5350T	_	plastic surface mounted package; 3 leads	SOT23

50 V, 3 A PNP low V_{CEsat} (BISS) transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		_	-2	Α
I _{CRP}	repetitive peak collector current	note 1	_	-3	А
I _{CM}	peak collector current	single peak	_	- 5	Α
I _B	base current (DC)		_	-0.5	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 2	_	300	mW
		T _{amb} ≤ 25 °C; note 3	_	480	mW
		T _{amb} ≤ 25 °C; note 4	_	540	mW
		T _{amb} ≤ 25 °C; notes 1 and 2	_	1.2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Operated under pulsed conditions: pulse width $t_p \le 100$ ms; duty cycle $\delta \le 0.25$.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
- 3. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- 4. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th (j-a)}	thermal resistance from junction to	in free air; note 1	417	K/W
	ambient	in free air; note 2	260	K/W
		in free air; note 3	230	K/W
		in free air; notes 1 and 4	104	K/W

Notes

- Device mounted on a printed-circuit board; single sided copper; tinplated; standard footprint.
- 2. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm².
- Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 6 cm².
- 4. Operated under pulsed conditions: pulse width $t_p \le 100$ ms; duty cycle $\delta \le 0.25$.

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

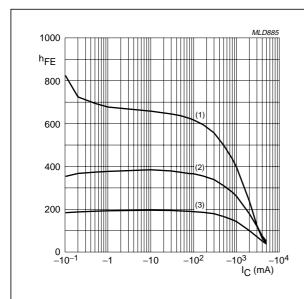
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	_	_	-100	nA
		$V_{CB} = -50 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	_	-100	nA
h _{FE}	DC current gain	$V_{CE} = -2 \text{ V}; I_{C} = -100 \text{ mA}$	200	_	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -500 \text{ mA}$	200	_	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -1 \text{ A}; \text{ note 1}$	200	_	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -2 \text{ A}; \text{ note 1}$	130	_	_	
		$V_{CE} = -2 \text{ V; } I_{C} = -3 \text{ A; note 1}$	80	_	_	
V _{CEsat}	collector-emitter saturation	$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	_	-90	mV
voltage	$I_C = -1 \text{ A}; I_B = -50 \text{ mA}$	_	_	-180	mV	
		$I_C = -2 \text{ A}$; $I_B = -100 \text{ mA}$; note 1	_	_	-320	mV
		$I_C = -2 \text{ A}$; $I_B = -200 \text{ mA}$; note 1	_	_	-270	mV
		$I_C = -3 \text{ A}$; $I_B = -300 \text{ mA}$; note 1	_	_	-390	mV
R _{CEsat}	equivalent on-resistance	$I_C = -2 \text{ A}; I_B = -200 \text{ mA}; \text{ note 1}$	_	90	135	mΩ
V _{BEsat}	base-emitter saturation	$I_C = -2 \text{ A}$; $I_B = -100 \text{ mA}$; note 1	_	_	-1.1	V
	voltage	$I_C = -3 \text{ A}$; $I_B = -300 \text{ mA}$; note 1	_	_	-1.2	V
V _{BEon}	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V; } I_{C} = -1 \text{ A; note 1}$	-1.2	_	_	V
f _T	transition frequency	$I_C = -100 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	100	_	_	MHz
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	_	35	pF

Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

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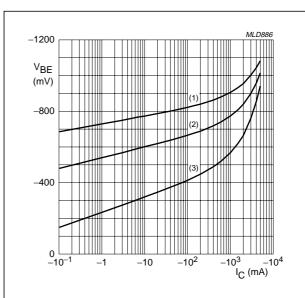
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 $V_{CE} = -2 V$.

- (1) T_{amb} = 150 °C.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

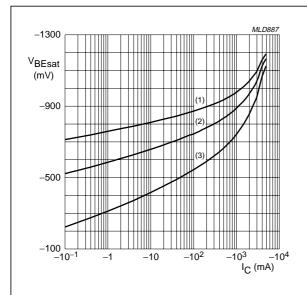
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = -2 V$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) T_{amb} = 150 °C.

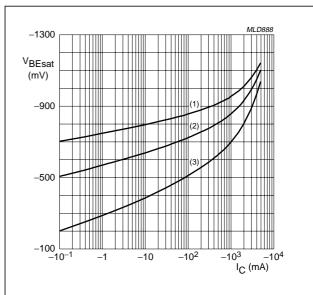
Fig.3 Base-emitter voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 10$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

Fig.4 Base-emitter saturation voltage as a function of collector current; typical values.



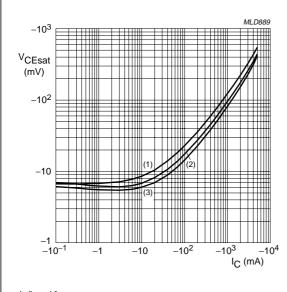
 $I_{\rm C}/I_{\rm B} = 20$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.

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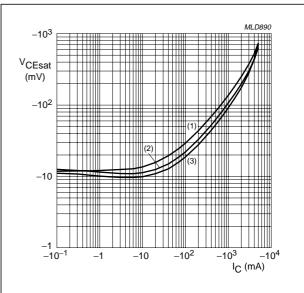
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 $I_{\rm C}/I_{\rm B} = 10.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

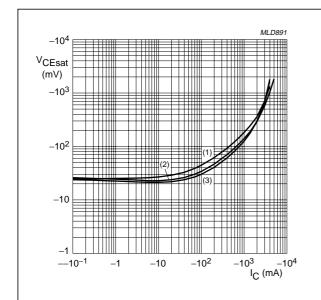
Fig.6 Collector-emitter saturation voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

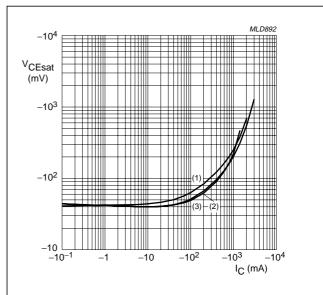
Fig.7 Collector-emitter saturation voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 50.$

- (1) T_{amb} = 150 °C.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.8 Collector-emitter saturation voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 100.$

- (1) T_{amb} = 150 °C.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.9 Collector-emitter saturation voltage as a function of collector current; typical values.

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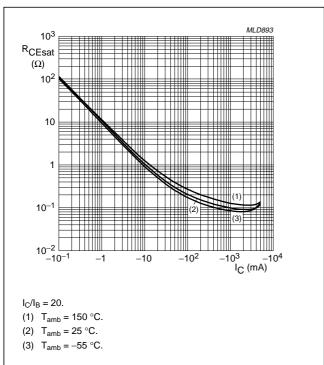


Fig.10 Equivalent on-resistance as a function of collector current; typical values.

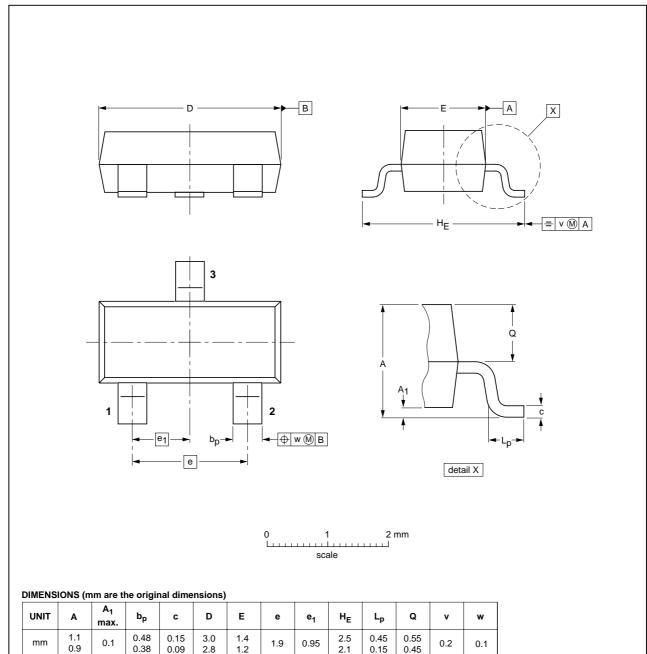
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PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



OUTLINE REFERENCES			EUROPEAN	ISSUE DATE	
IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	TO-236AB				-97-02-28- 99-09-13
	IEC	IEC JEDEC	IEC JEDEC EIAJ	IEC JEDEC EIAJ	IEC JEDEC EIAJ PROJECTION

50 V, 3 A PNP low V_{CEsat} (BISS) transistor

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